TOSHIBA PHOTOCOUPLER GaAs IRED & PHOTO-TRIAC TLP3020,TLP3021,TLP3022,TLP3023

OFFICE MACHINE HOUSEHOLD USE EQUIPMENT TRIAC DRIVER SOLID STATE RELAY

The TOSHIBA TLP3020, TLP3021, TLP3022 and TLP3023 consist of a photo-triac optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

: 100 mA (Max.)

- Peak Off-State Voltage : 400 V (Min.)
- Trigger LED Current
- : 30mA (Max.) (TLP3020) 15 mA (Max.) (TLP3021) 10 mA (Max.) (TLP3022) 5 mA (Max.) (TLP3023)

: UL1577, File No. E67349

- On-State Current
 - UL Recognized
 - Isolation Voltage : 5000 Vrms (Min.)
- Option (D4) Type

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- VDE Approved
- : DIN VDE0884 / 08.87, Certificate No. 68329

Maximum Operating Insulation Voltage: 630 VPK Highest Permissible Over Voltage: 6000 VPK

Note: When a VDE0884 approved type is needed, please designate the " Option (D4) "

		7.62mm pich	10.16 mm pich
		standard type	(LF2) type
• Creepage Distance	:	7.0 mm (Min.)	8.0 mm (Min.)
Clearance	:	7.0 mm (Min.)	8.0 mm (Min.)
Insulation Thickness	s :	0.5 mm (Min.)	0.5 mm (Min.)



PIN CONFIGURATION (TOP VIEW)



1: ANODE

2: CATHODE

3: N.C.

4: TERMINAL 1

6: TERMINAL 2

MAXIMUM RATINGS (Ta=25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT		
LED	Forward Current		IF	50	mA	
	Forward Current Derating (Ta ≥ 53°C)		∆l _F /°C	-0.7	mA/°C	
	Peak Forward Cur (100µs pulse, 100	rrent)pps)	I _{FP}	1	A	
	Power Dissipation	<u>ו</u>	PD	100	mW	
	Power Dissipation Derating (Ta ≥ 25°C)		∆P _D /°C	-1.0	mW/°C	
	Reverse Voltage		V _R	5	V	
	Junction Temperature		Tj	125	°C	
	Off-State Output T	Ferminal Voltage	V _{DRM}	400	V	
	On-Stage RMS	Ta=25°C		100	٣٨	
	Current	Ta=70°C	Ч(RMS)	50	IIIA	
с	On-State Current Derating (Ta ≥ 25°C)		∆I _T /°C	-1.1	mA/°C	
ECTO	Peak On-Stage Current (100 <i>µ</i> s pulse, 120pps)		ITP	2	A	
DET	Peak Nonrepetitive Surge Current (P _W =10ms, DC=10%)		ITSM	1.2	А	
	Power Dissipation		PD	300	mW	
	Power Dissipation Derating (Ta ≥ 25°C)		∆P _D /°C	-4.0	mW/°C	
	Junction Temperature		Tj	115	°C	
Stora	ge Temperature Rar	nge	T _{stg}	-55 ~ 150	°C	
Opera	ating Temperature R	lange	T _{opr}	-40 ~ 100	°C	
Lead	Soldering Temperat	ture (10s)	T _{sol}	260	°C	
Total I	Package Power Dis	sipation	PT	330	mW	
Total Package Power Dissipation Derating (Ta ≥ 25°C)		∆P _T /°C	-4.4	mW/°C		
Isolation Voltage (AC, 1 min., R.H. ≤ 60%) (Note 1)		BVS	5000	Vrms		

Note 1: Device considered a two terminal device :Pins 1, 2 and 3 shorted together and pins 4 and 6 shorted together.

RECOMMENDED OPERATING CONDISTIONS

CHARACTERISTICS	SYMBOL	MIN	TYP.	MAX	UNIT
Supply Voltage	V _{AC}	—	—	120	Vac
Forward Current	IF*	15	20	25	mA
Peak On-Stage Current	I _{TP}	—	—	1	А
Operating Temperature	T _{opr}	-25	—	85	°C

*: In the case of TLP3022

INDIVIDUAL ELECTRICAL CHARACTERISTICS (Ta=25°C)

	CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
	Forward Voltage	V _F	I _F =10mA	1.0	1.15	1.3	V
LED	Reverse Current	I _R	V _R =5V		_	10	μA
_	Capacitance	CT	V=0, f=1MHz	_	10	_	pF
DETECTOR	Peak Off-State Current	I _{DRM}	V _{DRM} =400V	_	10	100	nA
	Peak On-Stage Voltage	V _{TM}	I _{TM} =100mA	_	1.7	3.0	V
	Holding Current	Ι _Η	—	_	0.6	_	mA
	Critical Rate of Rise of Off- State Voltage	dv / dt	V _{in} =120Vrms, Ta=85°C (Fig.1)	200	500		V/µs
	Critical Rate of Rise of Commutating Voltage	dv / dt(c)	V _{in} =30Vrms, IF=15mA (Fig.1)	_	0.2		V/µs

COUPLED ELECTRICAL CHARACTERISTICS (Ta=25°C)

CHARACTERIS	TIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT	
Trigger LED Current	TLP3020		V _T =3V		_	30	mA	
	TLP3021	le		_	_	15		
	TLP3022	IFT			5	10		
	TLP3023			_	_	5		
Capacitance Input to Out	nput to Output C _S V _S =0, f=1MHz — 0.4		0.8	_	pF			
Isolation Resistance		R _S	V _S =500V (R.H. ≤ 60%)	5×10 ¹⁰	10 ¹⁴	_	Ω	
	B _{VS}		AC, 1 minute		_	_	V _{rms}	
Isolation Voltage			AC, 1 second (in oil)	_	10000	_	ν.	
			DC, 1 minute (in oil)	_	10000	_	v dc	

Fig. 1 dv/dt TEST CIRCUIT



 $I_{\rm F}$ – Ta









$$\Delta V_F/\Delta Ta - I_F$$







 $I_{FP} - V_{FP}$



NORMALIZED IFT – Ta

NORMALIZED I_H – Ta





NORMALIZED IDRM – Ta











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